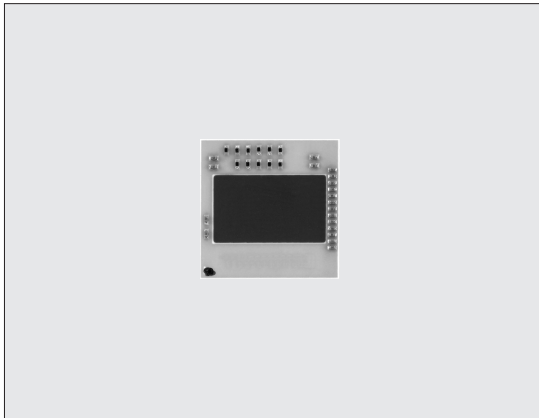
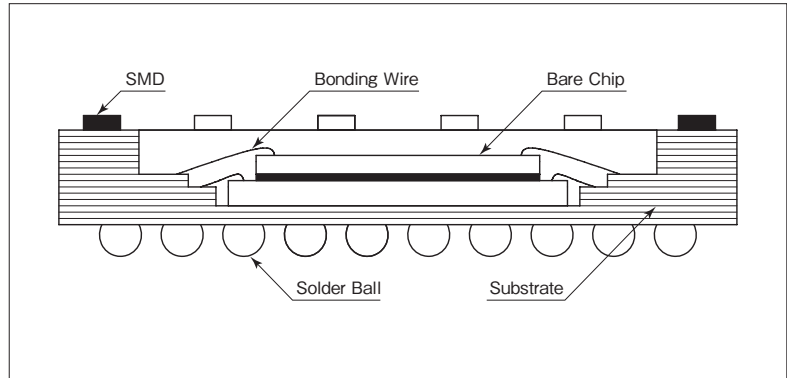


MCM ■ 多片模块·系统套装包装 (SiP)

Multi Chip Module • System in Package



■ 结构图 Construction



■ 特点 Features

- 由复数个半导体编入一个包装，实现系统的小型化，高功能化，标准化。
- 由于增大基板、多层精巧焊盘，使得线路面积的降低、配线距离缩短，因此能解除信号延迟的问题。
- 功能调整能实现组件高精度。
- 减少外部端子，降低贴装不良率。
- Plural semiconductors in one package offers downsized system with high performance and standardization.
- Wiring space saving by multilayer fine patterns on build-up substrate. No signal delay by shortened wiring distance.
- High precision modules by function trimming.
- Less mounting problem because of the decreasing number of the terminals.

■ 贴片规格 Mounting Specifications

项目 Item	单位 Unit	minimum	Standard	Maximum	Note	
基板外形尺寸 Substrate Dimension	mm	50×20	120×100	320×140		
基板厚度 Substrate Thickness	mm	0.3	—	1.6		
裸芯片管脚间距 Bare Chip Pad Pitch	μm	100	—	—		
裸芯片管脚尺寸 Bare Chip Pad Dimension	μm	70	—	—		
裸芯片管脚厚度 Bare Chip Thickness	mm	0.1	0.2	—		
封装高度 Molding Height	mm	0.3	1.0	1.2	芯片表面开始的高度 Height from the chip surface	
线长 Wire Length	mm	0.3	—	3.0		
线环高度 Wire Loop Height	μm	100	200	—		
线径 Wire Diameter	Al	μm	200	300	500	for Power Module
	Au	μm	20	25	40	
基板电镀 Plating	电解·无电解镀金 Electrical/non-electrical Au Plating					
基板 Substrate	<ul style="list-style-type: none"> • FR-4 • FR-5 • Alumina • LTCC • FPC 					

■ 包装规格 Package Specifications

项目 Item	内容 Content
端子间距 Terminal Pitch	0.8mm~
可焊接产品 Mountable device	<ul style="list-style-type: none"> • SMD • Bare Chip • Printed Resistor (Trimable)
可对应包装 Package	<ul style="list-style-type: none"> • SON • BGA • LGA
包装基材 Substrate for Package	<ul style="list-style-type: none"> • FR-4 • FR-5 • Alumina • LTCC